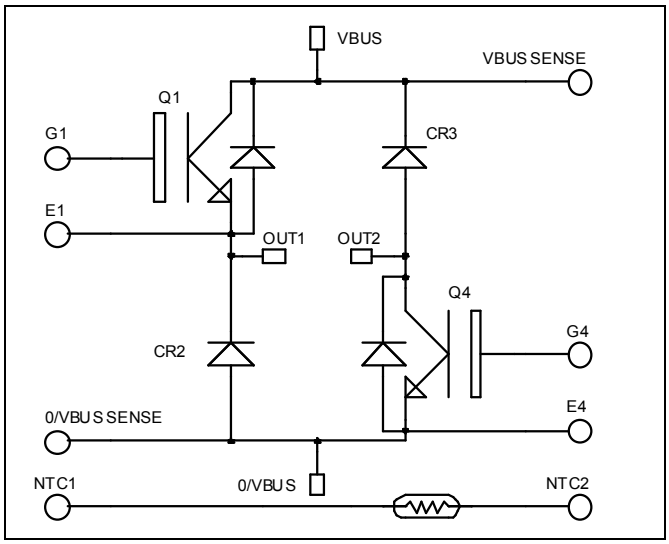
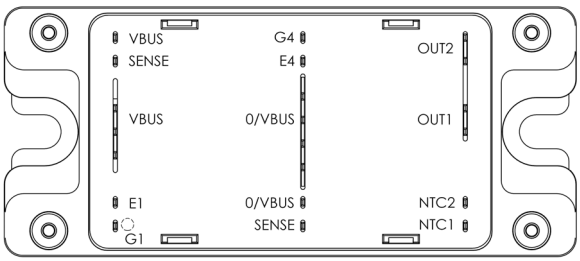
APTGT50DH120TG

Asymmetrical - Bridge
Fast Trench + Field Stop IGBT3
Power Module

V_{CES} = 1200V
I_C = 50A @ Tc = 80°C





Application

- Welding converters
- Switched Mode Power Supplies
- Switched Reluctance Motor Drives

Features

- Fast Trench + Field Stop IGBT3 Technology
  - Low voltage drop
  - Low tail current
  - Switching frequency up to 20 kHz
  - Soft recovery parallel diodes
  - Low diode VF
  - Low leakage current
  - RBSOA and SCSOA rated
- Kelvin emitter for easy drive
- Very low stray inductance
  - Symmetrical design
  - Lead frames for power connections
- High level of integration
- Internal thermistor for temperature monitoring

Benefits

- Stable temperature behavior
- Very rugged
- Solderable terminals for easy PCB mounting
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive T_C of V_{CEsat}
- Low profile
- RoHS Compliant

Absolute maximum ratings

Symbol	*Parameter*		*Max ratings*	*Unit*
V_{CES}	Collector - Emitter Breakdown Voltage		1200	V
I_C	Continuous Collector Current	T_C = 25°C	75	A
		T_C = 80°C	50	
I_{CM}	Pulsed Collector Current	T_C = 25°C	100	
V_{GE}	Gate – Emitter Voltage		±20	V
P_D	Maximum Power Dissipation	T_C = 25°C	277	W
RBSOA	Reverse Bias Safe Operating Area	T_j = 125°C	100A @ 1150V	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ T_j = 25°C unless otherwise specified

Electrical Characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
I_{CES}	Zero Gate Voltage Collector Current	V_{GE} = 0V, V_{CE} = 1200V				250	µA
$V_{CE(sat)}$	Collector Emitter Saturation Voltage	V_{GE} = 15V, I_C = 50A	T_j = 25°C		1.7	2.1	V
			T_j = 125°C		2.0		
$V_{GE(th)}$	Gate Threshold Voltage	V_{GE} = V_{CE}, I_C = 2mA		5.0	5.8	6.5	V
I_{GES}	Gate – Emitter Leakage Current	V_{GE} = 20V, V_{CE} = 0V				400	nA

Dynamic Characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
C_{ies}	Input Capacitance	V_{GE} = 0V V_{CE} = 25V f = 1MHz			3600		pF
C_{oes}	Output Capacitance				190		
C_{res}	Reverse Transfer Capacitance				160		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (25°C) V_{GE} = 15V V_{Bus} = 600V I_C = 50A R_G = 18 Ω			90		ns
T_r	Rise Time				30		
$T_{d(off)}$	Turn-off Delay Time				420		
T_f	Fall Time				70		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching (125°C) V_{GE} = 15V V_{Bus} = 600V I_C = 50A R_G = 18 Ω			90		ns
T_r	Rise Time				50		
$T_{d(off)}$	Turn-off Delay Time				520		
T_f	Fall Time				90		
E_{on}	Turn-on Switching Energy	V_{GE} = 15V V_{Bus} = 600V I_C = 50A R_G = 18 Ω	T_j = 125°C		5		mJ
E_{off}	Turn-off Switching Energy		T_j = 125°C		5.5		

Diode ratings and characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
V_{RRM}	Maximum Peak Repetitive Reverse Voltage			1200			V
I_{RM}	Maximum Reverse Leakage Current	V_R=1200V	T_j = 25°C			250	µA
			T_j = 125°C			500	
I_F	DC Forward Current		Tc = 80°C		50		A
V_F	Diode Forward Voltage	I_F = 50A	T_j = 25°C		1.4	1.9	V
			T_j = 125°C		1.3		
t_{rr}	Reverse Recovery Time	I_F = 50A V_R = 600V di/dt =2000A/µs	T_j = 25°C		150		ns
			T_j = 125°C		250		
Q_{rr}	Reverse Recovery Charge		T_j = 25°C		4.5		µC
			T_j = 125°C		9		
E_r	Reverse Recovery Energy		T_j = 25°C		2.1		mJ
			T_j = 125°C		4.2		

Temperature sensor NTC (see application note APT0406 on www.microsemi.com for more information).

Symbol	Characteristic	Min	Typ	Max	Unit
R_{25}	Resistance @ 25°C		50		kΩ
$B_{25/85}$	T_{25} = 298.15 K		3952		K

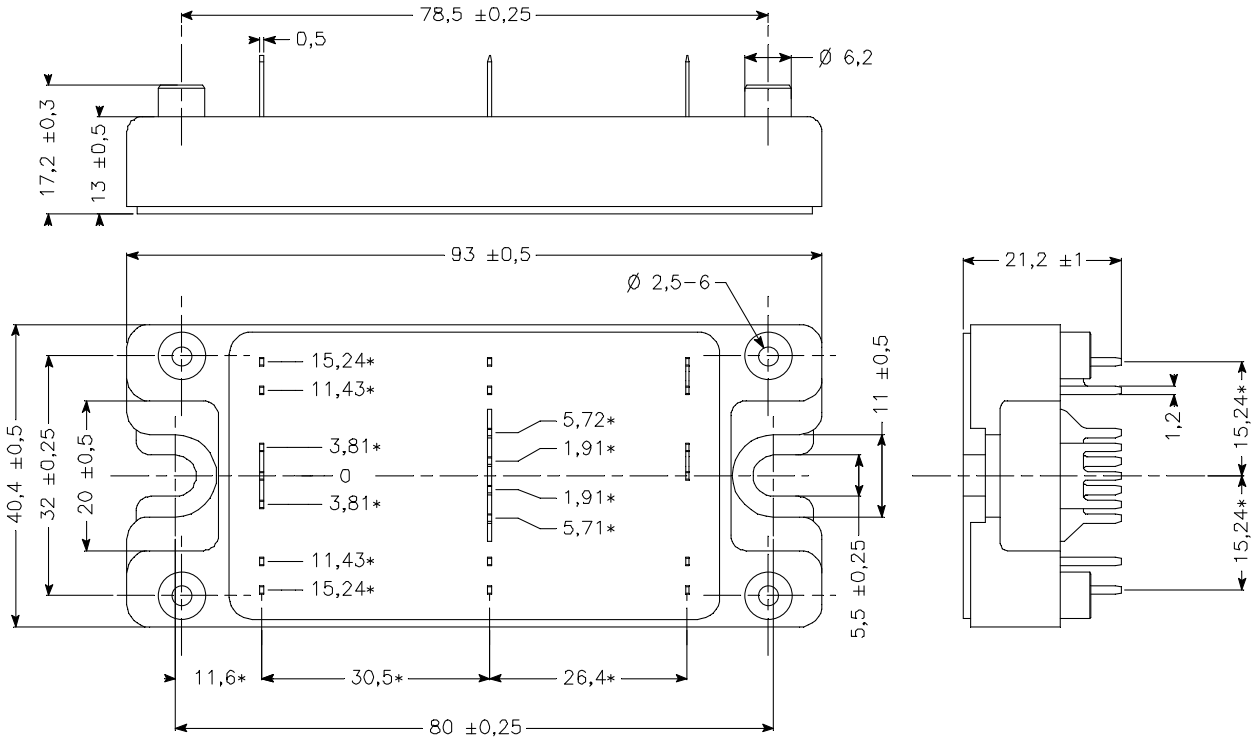
$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

T: Thermistor temperature
R_T: Thermistor value at T

Thermal and package characteristics

Symbol	Characteristic			Min	Typ	Max	Unit
R_{thJC}	Junction to Case Thermal Resistance		IGBT			0.45	°C/W
			Diode			0.58	
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000			V
T_J	Operating junction temperature range			-40		150	°C
T_{STG}	Storage Temperature Range			-40		125	
T_C	Operating Case Temperature			-40		100	
Torque	Mounting torque	To Heatsink	M5	2.5		4.7	N.m
Wt	Package Weight					160	g

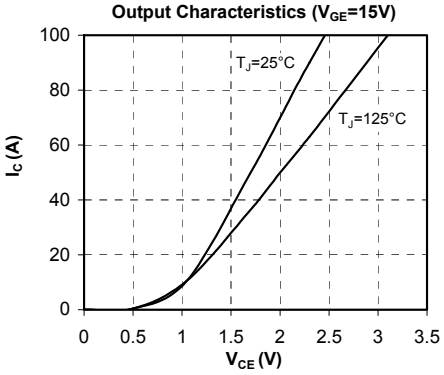
SP4 Package outline (dimensions in mm)

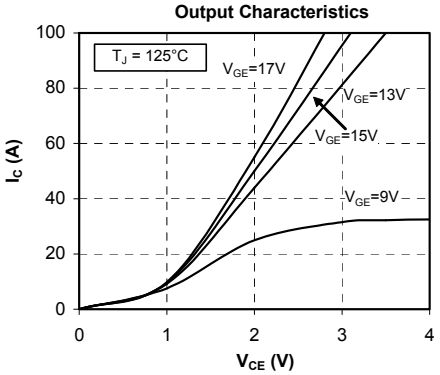


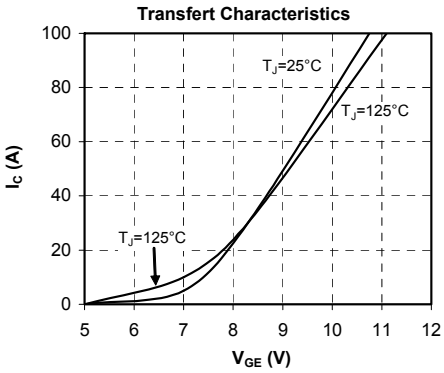
ALL DIMENSIONS MARKED " * " ARE TOLERENCED AS : ⌖Ø1

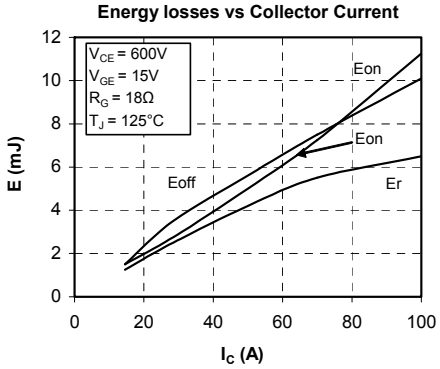
See application note APT0501 - Mounting Instructions for SP4 Power Modules on www.microsemi.com

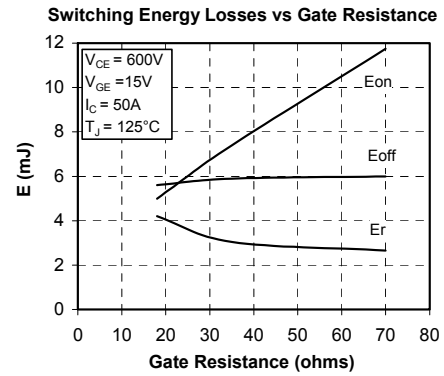
Typical Performance Curve

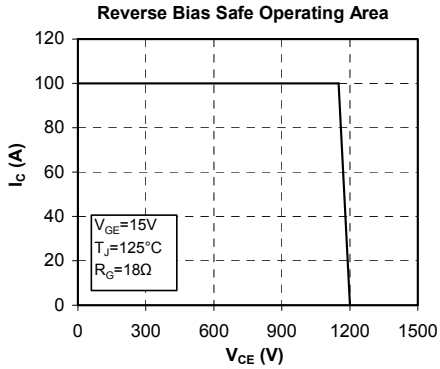


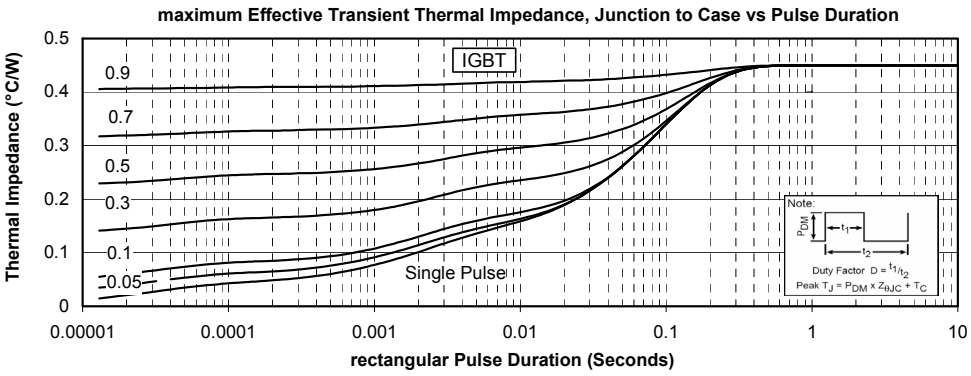


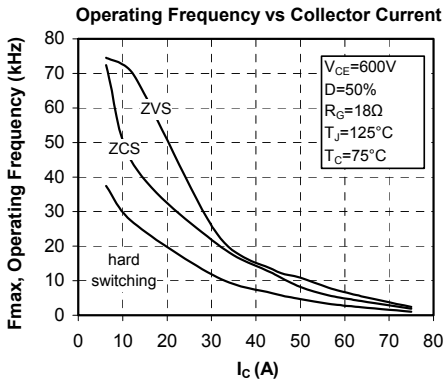


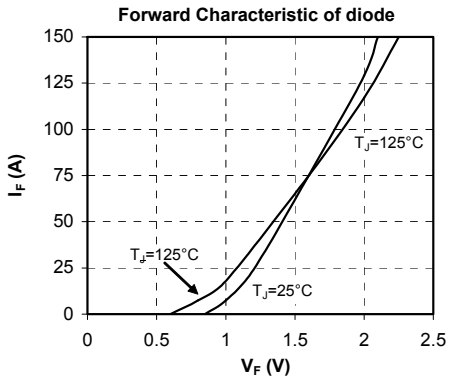


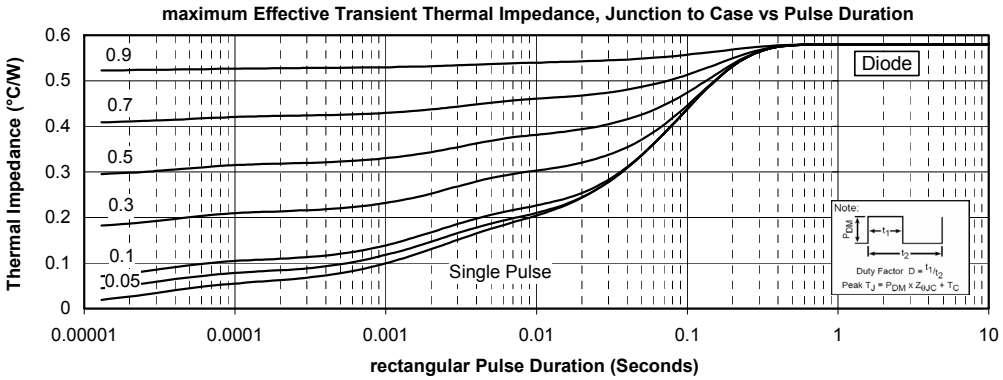












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